

## **CLAIMS**

What is claimed is:

1. A system comprising:
  - a bowl having an interior region and an interior surface;
  - a wafer platform disposed within the interior region of the bowl;
  - a wafer spindle coupled to the wafer platform, the wafer spindle capable of spinning the wafer platform such that an excess amount of photoresist deposited upon a wafer placed upon the wafer platform is propelled to the interior surface of the bowl; and
  - a perimeter drain formed within the bowl such that the excess amount of photoresist propelled from the wafer proceeds through the perimeter drain to a photoresist recovery container.
2. The system of claim 1 wherein the photoresist recovery container is coupled to the bowl via a recovery drainpipe.
3. The system of claim 2 further comprising:
  - a recovery drainpipe block capable of being positioned in front of the recovery drainpipe to prevent contaminants from entering the recovery drainpipe.
4. The system of claim 1 wherein the perimeter drain is formed within the interior surface of the bowl level with a wafer rotation position.

5. The system of claim 1 wherein a solvent-rich environment is maintained within the recovery drainpipe.
6. The system of claim 5 wherein the solvent-rich environment contains solvent vapor.
7. The system of claim 6 wherein the solvent vapor comprises a solvent contained within the photoresist deposited upon the wafer.
8. The system of claim 1 further comprising:  
one or more additional perimeter drains formed within the bowl to recover one or more additional types of photoresists in corresponding photoresist recovery containers.
9. A system comprising:  
a bowl having an interior region and an interior surface;  
a wafer platform disposed within the interior region of the bowl;  
a wafer spindle coupled to the wafer platform, the wafer spindle capable of spinning the wafer platform such that an excess amount of photoresist deposited upon a wafer placed upon the wafer platform is propelled to the interior surface of the bowl;  
a photoresist recovery container coupled to the bowl with a recovery drainpipe such that a solvent used as part of a bowl wash process effected after the excess amount of photoresist has been propelled to the interior surface of the bowl will cause the excess amount of photoresist to proceed through the recovery drainpipe into the photoresist recovery container; and

a recovery drainpipe block capable of being positioned in front of the recovery drainpipe to prevent contaminants from entering the recovery drainpipe.

10. The system of claim 9 further comprising:

a waste drainpipe capable of draining waste material from the interior region of the bowl and;

a waste drainpipe block capable of being positioned in front of the waste drainpipe to prevent the excess amount of photoresist from proceeding through the waste drainpipe.

11. The system of claim 10 further comprising:

a waste receptacle coupled to the bowl via the waste drain pipe.

12. The system of claim 9 wherein the solvent comprises a solvent contained within the photoresist deposited upon the wafer.

13. The system of claim 9 further comprising:

one or more additional photoresist recovery containers, each corresponding to a particular photoresist, coupled to the bowl with a corresponding recovery drainpipe such that a solvent used as part of a bowl wash process effected after an excess amount of a particular photoresist has been propelled to the interior surface of the bowl, will cause the excess amount of the particular photoresist to proceed through the corresponding recovery drainpipe into the corresponding photoresist recovery container.

14. A method comprising:

depositing an amount of photoresist upon a substrate, the amount of photoresist more than necessary to coat the substrate, the photoresist containing a first solvent;

spinning the substrate within a bowl such that an excess amount of photoresist is propelled off of the substrate to an interior surface of the bowl;

rinsing the bowl with a second solvent such that some of the excess amount of photoresist is suspended in the second solvent producing a photoresist/solvent composition; and

recovering the photoresist/solvent composition.

15. The method of claim 14 wherein the first solvent and the second solvent are the same type of solvent.

16. The method of claim 15 further comprising:

evaporating an amount of the solvent from the photoresist/solvent composition to produce a useable photoresist.

17. The method of claim 15 further comprising:

effecting a bead-edge removal process on the wafer;

rinsing the bowl with a third solvent; and

preventing the third solvent from contacting the photoresist/solvent composition.

18. A method comprising:

depositing an amount of photoresist upon a substrate, the amount of photoresist more than necessary to coat the substrate;

spinning the substrate within a bowl such that an excess amount of photoresist is propelled off of the substrate to an interior surface of the bowl;

recovering a portion of the excess amount of photoresist; and

treating the recovered portion of the excess amount of photoresist such that the recovered portion of the excess amount of photoresist is rendered usable.

19. The method of claim 18 wherein recovering some of the excess amount of photoresist includes providing a perimeter drain formed within the bowl such that the excess amount of photoresist propelled from the wafer proceeds through the perimeter drain to a photoresist recovery container via a recovery drainpipe.

20. The method of claim 18 wherein a solvent-rich environment is maintained within the recovery drainpipe.

21. The method of claim 20 wherein the solvent-rich environment contains solvent vapor.

22. The method of claim 21 wherein the solvent vapor comprises a solvent contained within the photoresist deposited upon the wafer.

23. The method of claim 22 wherein treating the recovered portion of the excess amount of photoresist includes adding solvent to the recovered portion of the excess amount of photoresist.

24. The method of claim 23 further comprising:  
filtering the recovered portion of the excess amount of photoresist.

25. The method of claim 18 wherein recovering some of the excess amount of photoresist includes rinsing the bowl with a solvent such that some of the excess amount of photoresist is suspended in the solvent, producing a photoresist/solvent composition, and recovering the photoresist/solvent composition.

26. The method of claim 25 wherein treating the recovered portion of the excess amount of photoresist includes evaporating an amount of the solvent from the photoresist/solvent composition.

27. The method of claim 26 further comprising:  
filtering the photoresist/solvent composition.